



ELECTRONIC & PHOTONIC PACKAGING DIVISION

MISSION: The Electronic and Photonic Packaging Division (EPPD) of ASME has as its objectives international cooperation, understanding, and promotion of efforts and disciplines in Microelectronics, Photonics, RF and Micro-Electro-Mechanical Systems Packaging Engineering. The Division is concerned with all design and engineering aspects related to theoretical (analytical and computer-aided) and experimental problems and results associated with the application of methods and approaches of engineering and applied mechanics to the analysis, design, manufacturing, testing and operation of microelectronics, optoelectronics and photonics components, devices, equipment and systems.

EPPD Core Competencies

- Provide information transfer among its members through IMECE program, InterPACK conferences, Journal of Electronic Packaging and associated publications.
- Provide networking structure at conference and committee activity levels.
- Provide interactions with other Divisions: K-16 of Heat Transfer, Applied Mechanics, MEMS and Nanotechnology.
- Maintain effective interrelationship between industrial and academic interests.

Divisional Organization

- Executive Committee
 - Elected according to the Bylaws for a five year term.
 - Rotates from Member-at-large to Chair.
 - Should have equal industrial and academic representation.
- Technical Committee
 - For the technical program in IMECE.
 - For the technical program in InterPACK.
 - For the technical needs of the packaging community.
- Advisory Committee
 - For Division consultation and policy development.
 - For awards and recognitions.
 - For nominations and recruitment.
- Ad-hoc Committees (formed as needed)

EPPD Issues and Concerns

- Develop alliances with MEMS Division and Nanotechnology Institute on the packaging issue: transfer our expertise in this area to other division/institute.
- New committee structure to improve and grow IMECE program and make it more flexible to address membership needs.
- Newsletter and website development and maintenance need to be done in order to better serve the membership.
- Local technical chapters need to be developed and effectively integrated with current practices.
- Division must continue to increase its financial growth in order to support awards, scholarships and honors, and to independently sponsor conferences.
- Need to address membership concerns of how we can better serve them, provide career growth assistance and technical assistance.

Major Activities

- IMECE Program
 - Organized 20+ sessions each year in IMECE on topics in structural and stress analysis, modeling and reliability, materials and processing, thermal management of microelectronic systems, MEMS and nano scale packaging problems.
 - Co-sponsored sessions with Electronic and Photonic Tracks, K-16 of Heat Transfer and MEMS Divisions.
 - Sponsored receptions/dinners for recognition/award presentation.
- InterPACK Conferences (Odd Years)
 - Flagship conferences owned and organized by EPPD.
 - Provide an international forum for the packaging community.
 - Program organization and development is equally divided between industry and academia.
 - InterPACK series was recognized as “Hawaiian” conferences from 1995 to 2003, rotating among various islands of Hawaii.
 - InterPACK was moved back to the continent since 2005.
 - See separate frame for InterPACK’07 and ’09.
- IThERM Conferences (Even Years)
 - Currently owned by IEEE CPMT Society and co-located with ECTC.
 - Many organizers were EPPD officers or members.
- JOURNAL OF ELECTRONIC PACKAGING
 - Published quarterly.
 - Best paper and associate editor awards conferred yearly.
- DIVISIONAL COMMITTEE ACTIVITY
 - Active open meetings at IMECE and InterPACK with attendance of 20-40 participants.
 - Forum allowed membership concerns and emerging topics to be addressed.
 - Recruiting mechanism for IMECE and InterPACK program chairs and Divisional leaders.

InterPACK 2011 July 6-8, 2011 Portland, Oregon

- EPPD continues to be the primary sponsor of InterPACK, with co-sponsorship from the MEMS Division, the Nanotechnology Institute, and the Heat Transfer Division.
- The Organizing Committee is working to increase attendance to 800-1000 attendees, up from about 500